

Metal Material Properties Table 1

※ Published data is for reference only

Material		Metals with high melting point					Alloys				
		Tungsten	Molybdenum	Tantalum	Niobium	Titan	Alloy (W-Cu)	Alloy (Mo-Cu)	Heavy alloy Heavy metal (W-I)	Sealing alloy (Kovar)	Sealing alloy (Kovar)
Data Unit		W	Mo	Ta	Nb	Ti	W-Cu	Mo-Cu	W:90% Cu:11%	FeNiCo (sintered)	FeNiCo (HIP)
Material symbol		99.9%~99.99%	99.9%~99.99%	99.9%	99.99%	99.8%~99.98%	W:89% Cu:11%	Mo:65% Cu:35%	W:90%	Ni:29% Co:17% Fe:53.5% Mn:0.3% Si:0.2%	Ni:29% Co:17% Fe:53.5% Mn:0.3% Si:0.2%
Component amount [%]		19.3	10.2	16.6	8.47	4.54	17.00	9.70	17.0	8.0	8.35
Machining properties	Hardness	Vickers hardness Hv1	[GPa]	4.20	2.60	0.69~1.20	0.50~0.80	3.00	1.70	<3.20(Hv ₁₀)	1.60
	Tensile strength	20°C	[MPa]			207	124	270~410(1 type-RT)	>480	>280	590
		600°C	[MPa]			200(100°C)		340~510(2 type-RT)		690 (Compressive)	
		800°C	[MPa]			175(200°C)		480~620(3 type-RT)		2.0 impact value	
		1000°C	[MPa]			160(250°C)		550~750(4 type-RT)			
	Yield strength		[MPa]			138	85			510	270
	Dilation		[%]			20	25			0.4	35
	Flexural rigidity		[GPa]	1900						1.4	
	Young's modulus		[GPa]	403	327	185	103	106	330	220	280
	Poisson's ratio		-		0.32	0.35	0.38	0.34			
Thermal properties	Max. use temp	Depending on atmosphere	[°C]	3000	1900	700 and more					
	Recrystallization temperature		[°C]	1150~1350	900~1200	900~1400					
	Melting point		[°C]	3387	2623	3017	2468	1668			1450
	Boiling point		[°C]	5527	4827						
	Linear expansion coefficient	RT	[*10 ⁻⁶ /°C]			5.10					
		RT~100°C	[*10 ⁻⁶ /°C]	4.5	5.2		7.1	8.4	6.1	8.6	6.0
		RT~500°C	[*10 ⁻⁶ /°C]	4.6	5.7	3.6			6.4(300°C)	9.2(300°C)	6.2(300°C)
		RT~1000°C	[*10 ⁻⁶ /°C]	4.6	5.75				6.7(450°C)	9.6(450°C)	6.2(450°C)
		RT~1500°C	[*10 ⁻⁶ /°C]	5.4(2000°C) 6.6(3000°C)	6.51						6.0
	Thermal conductivity	20°C	[W/(m·K)]	168	142			17	180	210	90
		100°C	[W/(m·K)]	159	138	56	52		176	205	
		500°C	[W/(m·K)]	122	122						
		1000°C	[W/(m·K)]	111	105						
		1500°C	[W/(m·K)]	92.98(2000°C)	84						
	Specific heat		[J/(kg·K)]	140(20°C) 140(500°C)	260(20°C) 280(500°C)	78	272	520	160	320	460
Electrical characteristics	Electric conductivity		[%I.A.C.S]					>25	>47	15	
	Volume resistivity	20°C	[μΩ·cm]	5.5(20°C) 18.0(500°C)	5.7(20°C) 17.6(500°C)	14.7	14.5	47.0	5.3	3.5	12.0
Magnetic characteristics	Permeability		[Km]							<1.05	
	Susceptibility		[Xm]							0.00022	
Chemical reactivity	Liquid	hydrochloric acid	Loss	Slightly melts in 100°C diluted or concentrated hydrochloric acid							
		hydrochloric acid	Loss	no reaction							
		sulfuric acid	Loss	Slightly melts in heated diluted sulfuric acid Heats in concentrated sulfuric acid							
		sulfuric acid	Loss	Promptly melts in around 200°C Concentrated sulfuric acid							
		nitric acid	Loss	Slightly melts in diluted sulfuric acid Heats slightly in concentrated sulfuric acid							
		caustic soda (sodium hydroxide)	Loss	No reaction in diluted sulfuric acid Heats slightly in concentrated sulfuric acid							
		caustic soda (sodium hydroxide)	Loss	Almost not affected in solution Rapid reaction for molten salt							
		air or oxygen	Loss	Slightly oxidizes (discoloration) In around 400°C starts to oxidize to dioxide							
	Gas	air or oxygen	Loss	In above 700°C tungsten trioxide forms and suddenly oxidizes							
		vapor	Loss	Promptly oxidizes in red heat state							
		nitrogen	Loss	In about 2300°C and above forms a nitride							
		carbon monoxide	Loss	In around 1000°C and above explosive In about 2000°C forms a carbide							
		carbon dioxide	Loss	From about 1200°C forms an oxide							
		hydrogen	Loss	no reaction							
		hydrofluoric acid	Loss	Forms a fluoride in room temperature							
		chlorine	Loss	From 250°C to 300°C forms a chloride							
		bromine	Loss	Forms a bromide in red heat state							
		iodine	Loss	Forms an iodide in red heat state							
	Solid body	ammonia	Loss	Does not react in room temperature							
		hydrogen sulfide	Loss	Surface reaction occurs while in red heat state							
		sulfur	Loss	Slightly reacts in room temperature							
	carbon, graphite	Loss		From around 400°C starts to oxidize and embrittle From 1400°C forms carbon dioxide							
Features & applications			High thermal conductivity					Thermal expansion coefficient is variable	Easy to roll or presswork		
Remarks										For sealing hard glass Electronic components	For sealing hard glass Electronic components